ABSTRACT

A method and a device for applying a sealant to an IC having bumps, which can solve a cobwebbing problem when a dispense nozzle is raised after the sealant has been applied and implement a productivity improvement; specifically, a method and a device for applying a sealant to an IC having bumps, wherein a dispense nozzle (12) is raised in a first stage (E) at a low speed simultaneously with the stop of dispensing until the first stage (E) covers a specified height and then it is raised in a second stage (F) at a high seed. The above design, in which the dispense nozzle (12) is raised in the first stage (E) at a low speed after the application of the sealant (2) and the nozzle (12) is then raised at a high speed and in a short time in the second stage (F), can positively break off the sealant (2) without inducing cobwebbing and enhance productivity.